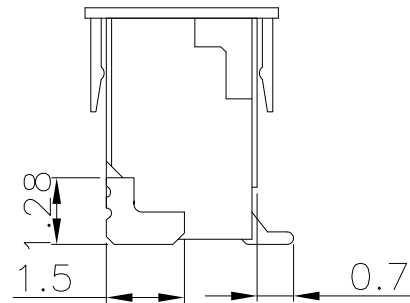
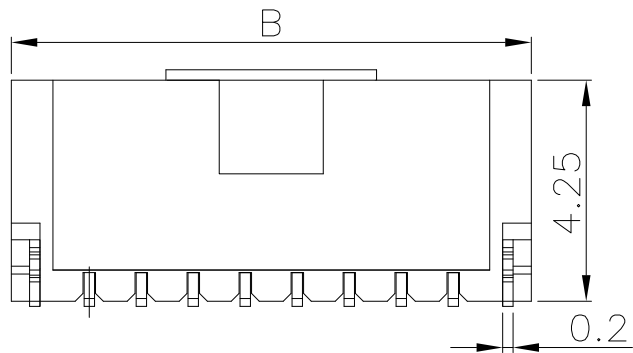


P.C.B LAYOUT MOUNTING PATTERN

PIN NO.	DIMENSION	
	A	B
02	1.00	4.00
03	2.00	5.00
04	3.00	6.00
05	4.00	7.00
06	5.00	8.00
07	6.00	9.00
08	7.00	10.00
09	8.00	11.00
10	9.00	12.00
11	10.00	13.00
12	11.00	14.00
13	12.00	15.00
14	13.00	16.00
15	14.00	17.00
16	15.00	18.00
17	16.00	19.00
18	17.00	20.00
19	18.00	21.00
20	19.00	22.00



- 1.MATERIAL
- HOUSING:HTN
- CONTACT:PHOSPHOR BRONZE
- SOLDER PAD:BRASS
- 2.PLATING: TIN OVER NICKEL
- 3.SPECIFICATION
- CURRENT RATING:1A AC,DC
- VOLTAGE RATING:250V AC,DC
- TEMPERATURE RANGE:-25C~+85C
- CONTACT RESISTANCE:20M MAX.
- INSULATION RESISTANCE:1000M MIN.
- WITHSTANDING VOLTAGE:500V AC/MINUTE

ITEM NO.	DESCRIPTION	DRAWN	DATE
4	更新材質	Jack	121422
3	更新PCB LAYOUT	Jack	091420
2	更新PCB LAYOUT	Jack	032118
1	更新B尺寸標示位置	Jack	101515

東莞市高迪電子有限公司
DONG GUAN GAO DI ELECTRONICS CO., LTD

TOLERANCE UNLESS OTHERWISE STATED :
 Up to 5 ±0.2
 Above 5 ~ 15 ±0.3
 Above 15 ~ 30 ±0.4
 Above 30 ~ 50 ±0.5
 Angle ±0.3

3RD. ANGEL'S



UNITS

MM

DRAWN BY:	DATE
Jack Lu	12/14/22
CHECKED BY:	DATE
Jacky Chen	12/14/22
APPROVED BY:	DATE
Tony Kao	12/14/22

MAT'L	TITLE	CONNECTOR
	MODLE	WAFER 1.0 SMT 180度(JST)
SCALE	1 : 1	DWG NO. WF-1000VSxx-S304
SHEET NO.	1 of 1	PART NO. WF-1000VSxx-S304
		SIZE A4
		VER R4